

/ Descriptions

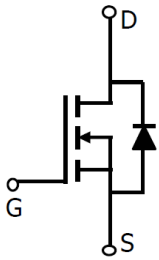
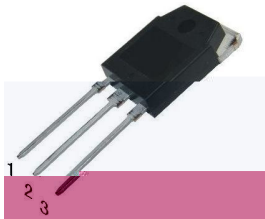
N TO-3PH

N-Channel MOSFET in a TO-3PH Plastic Package.

/ Features $R_{DS(ON)}$ Q_g Fast Intrinsic Rectifier, Low $R_{DS(ON)}$ and Q_g , Low Package Inductance**/ Applications**

GF0GF

Switch-Mode and Resonant-Mode Power Supplies, DC-DC Converters, Laser Drivers, AC and DC Motor Drives, Robotics and Servo Controls.

/ Equivalent Circuit**/ Pinning**

PIN1 Gate

PIN 2 Drain

PIN 3 Source

/ h_{FE} Classifications & Marking

See Marking Instructions.

BRCS26N50PH

Rev.A Jul.-2019

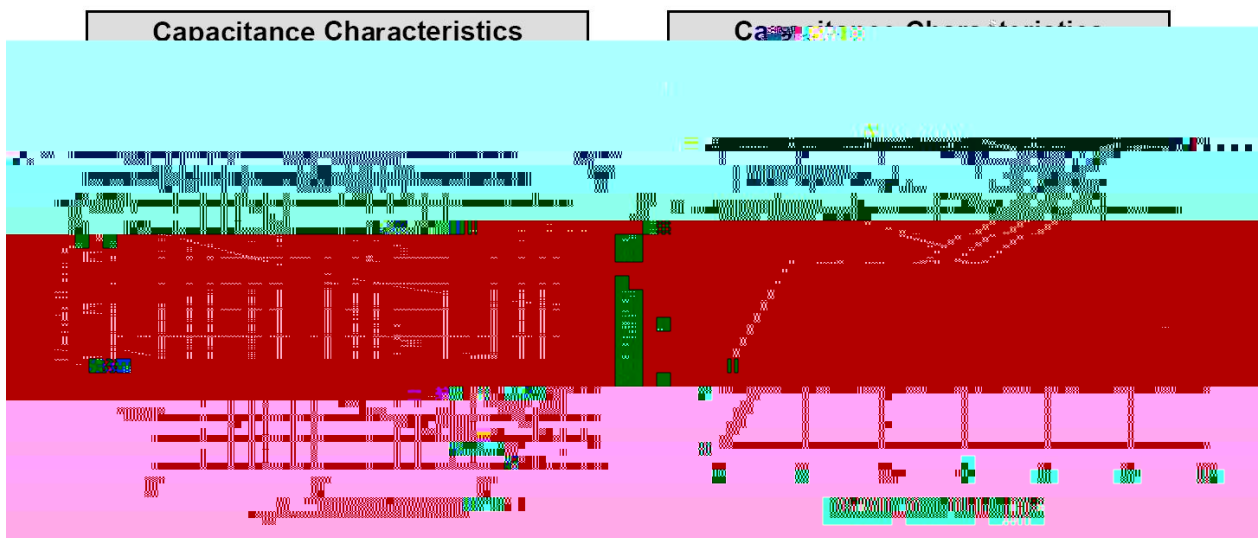
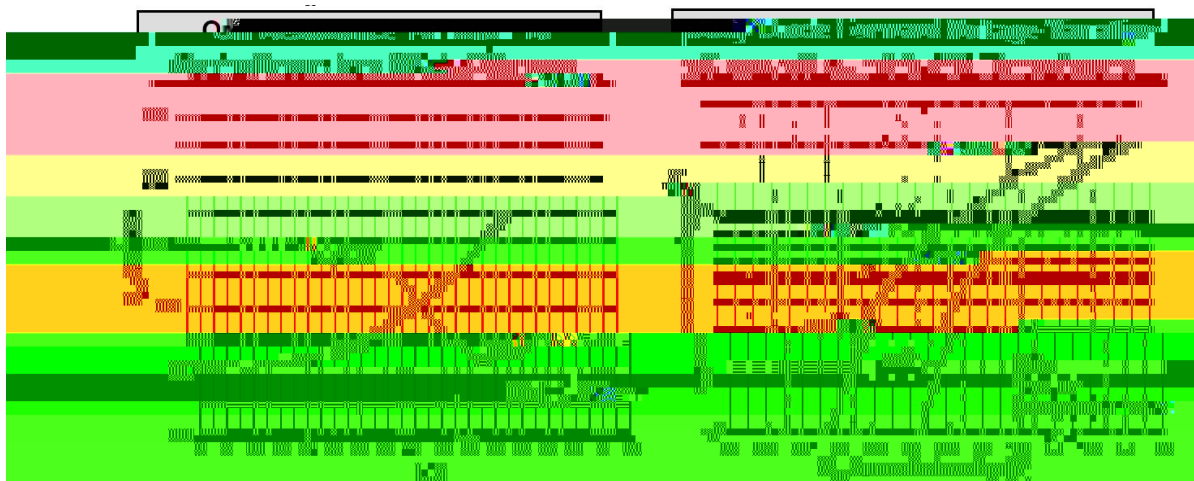
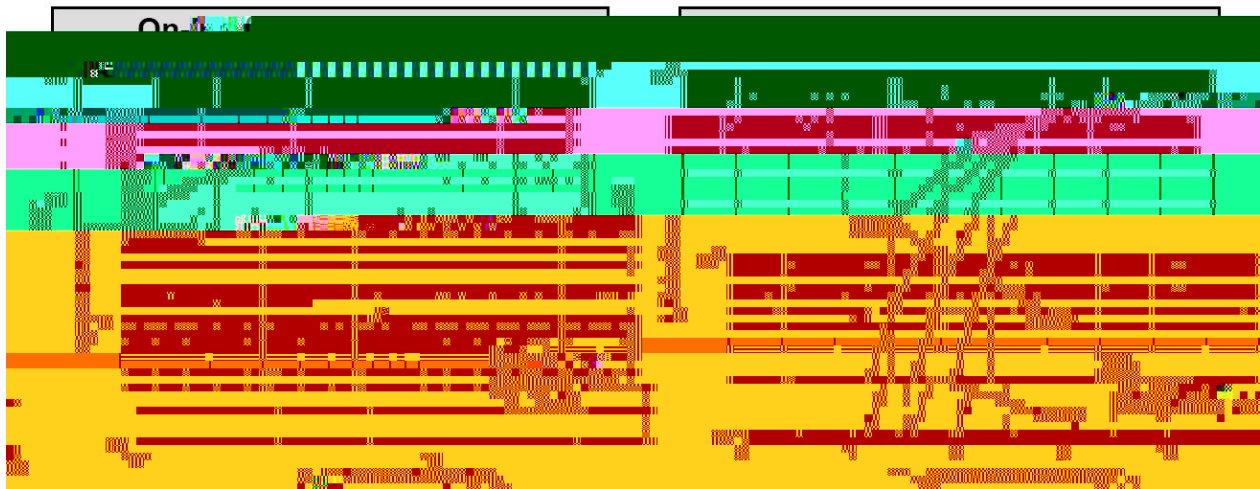
Parameter	Symbol	Rating	Unit
Drain Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Continuous- Current(Note 1)	$I_D(T_c=25^\circ\text{C})$	26	A

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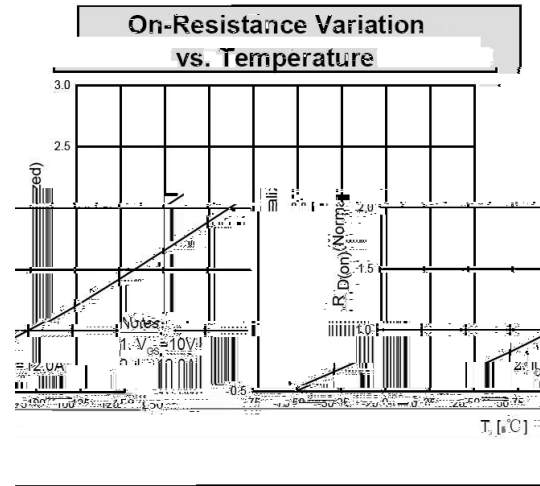
Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$	$I_D=250\mu A$	500			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=500V$	$V_{GS}=0V$			1	

/ Electrical Characteristic Curve

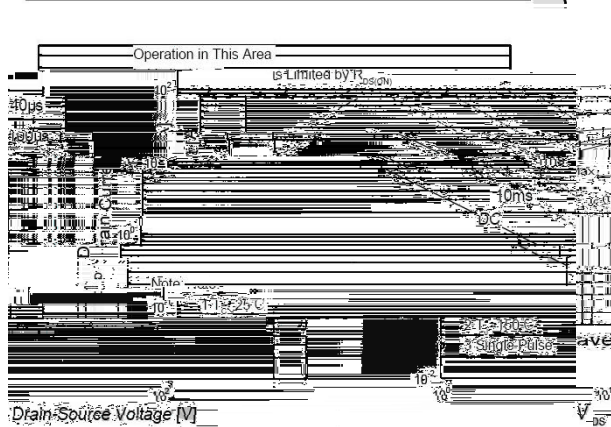


/ Electrical Characteristics(Ta=25 –)

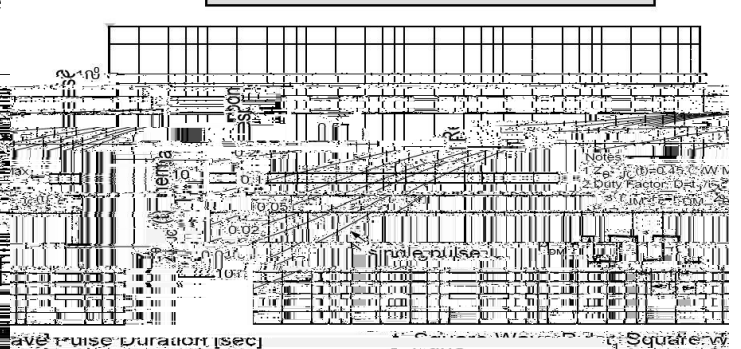
Breakdown Voltage Variation



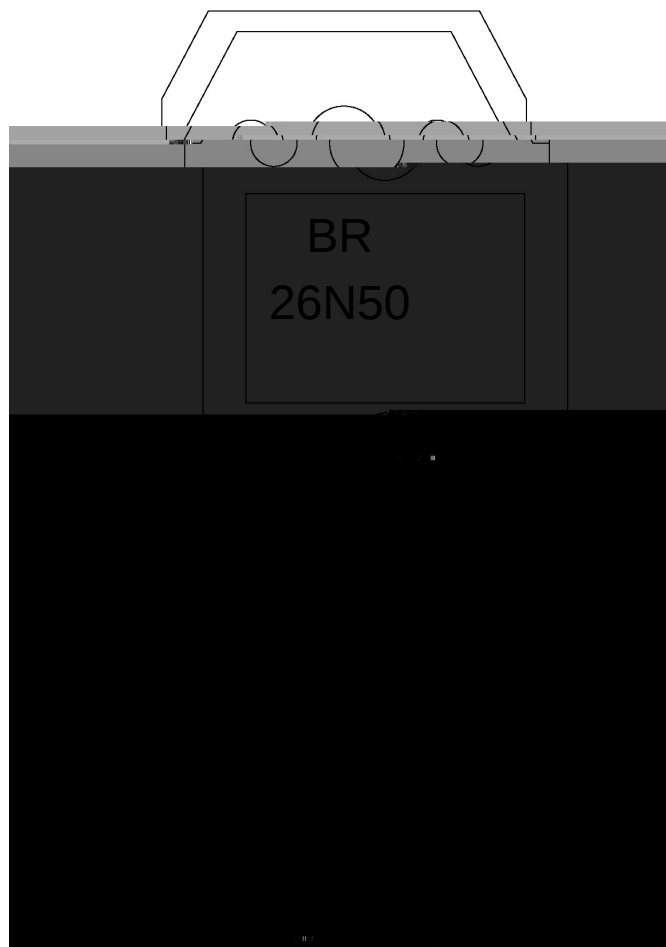
Maximum Safe Operating Area



Transient Thermal Response Curve



/ Marking Instructions



BR=

26N50

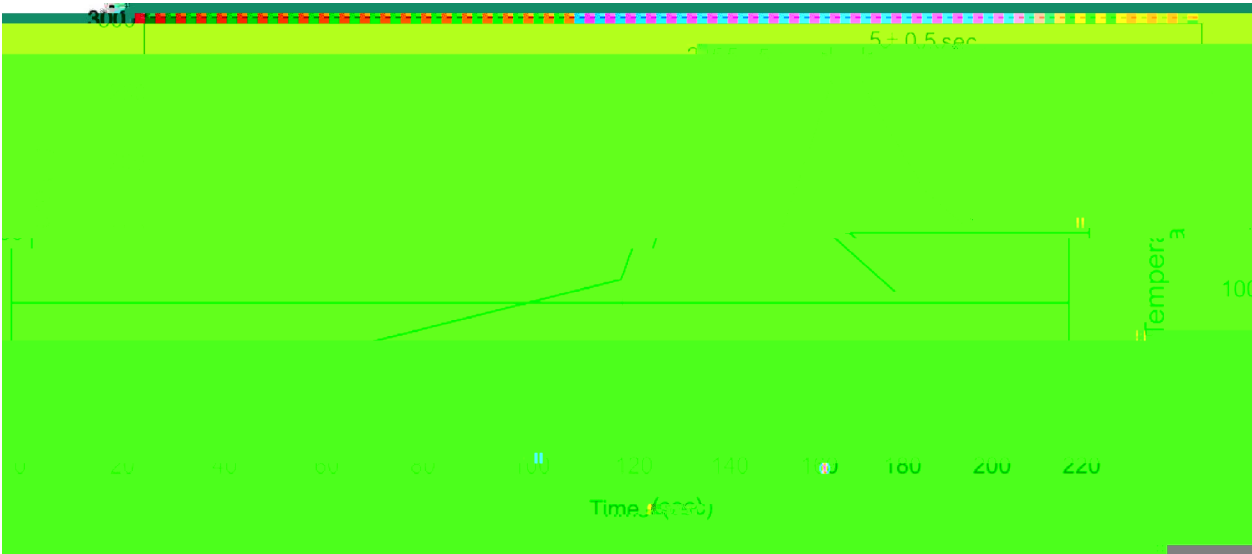
Note:

BR: Company Code.

26N50: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension		(unit mm ³)

/ Notices